

TCML1-11X+

50Ω

600 to 1100 MHz

FEATURES

- Wideband, 600 to 1100 MHz
- Balanced transmission line
- Excellent amplitude unbalance. 0.6 dB typ.
- · Excellent phase unbalanced, 8 deg typ.
- · Plastic base with solder plated leads
- · Aqueous washable

APPLICATIONS

- Cellular
- Baluns
- Impedance matching



Generic photo used for illustration purposes only

CASE STYLE: DB1627

+RoHS Compliant
The +Suffix identifies RoHS Compliance.
See our website for methodologies and qualification

ELECTRICAL SPECIFICATIONS AT 25°C

Parameter	Frequency (MHz)	Min.	Тур.	Max.	Units
Impedance Ratio			1		Ohm
Frequency Range		600		1100	MHz
Insertion Loss*	600 - 1100	_	2	_	dB
INSERTION LOSS	700 - 1000	_	1	_	ив

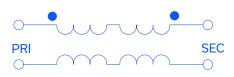
 $^{^{\}star}$ Insertion Loss is referenced to mid-band loss, 0.4 dB typ.

MAXIMUM RATINGS

Parameter	Ratings
Operating Temperature	-20°C to 85°C
Storage Temperature	-55°C to 100°C
RF Power	0.25 W
DC Current	30 mA

Permanent damage may occur if any of these limits are exceeded.

CONFIGURATION G



REV. C ECO-013883 TCML1-11X+ IG/CP/AM 220623





TCML1-11X+

50Ω

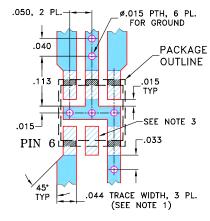
600 to 1100 MHz

PAD CONNECTIONS

PRIMARY DOT	6
PRIMARY	4
SECONDARY DOT	1
SECONDARY	3
NOT USED	2,5

PRODUCT MARKING: FJ

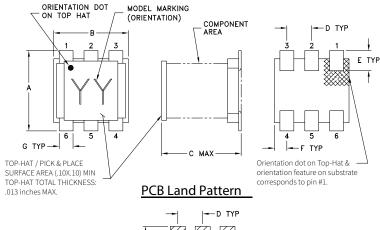
DEMOBOARD MCL P/N: TB-TCML1-11X+ SUGGESTED PCB LAYOUT (PL-244)

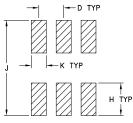


- 1. TRACE WIDTH IS SHOWN FOR ROGERS RO4350B WITH DIELECTRIC THICKNESS .020" ± .0015"; COPPER: 1/2 OZ. ON EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
- 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
- 3. THIS PAD IS NOT REQUIRED FOR AT224 CASE STYLE.

DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER) DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

OUTLINE DRAWING





SUGGESTED LAYOUT TOLERANCE TO BE WITHIN ±.002

OUTLINE DIMENSIONS (Inches)

F	Е	D	С	В	Α
.025	.040	.050	.160	.150	.160
0.64	1.02	1.27	4.06	3.81	4.06
wt		K	J	Н	G
grams		.030	.190	.065	.028
0.15		0.76	4.83	1.65	0.71

TAPE & REEL INFORMATION: F47



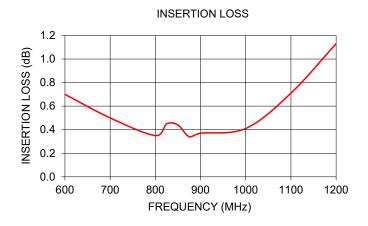
TCML1-11X+

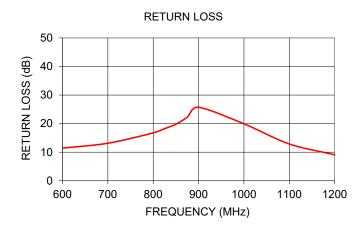
50Ω

600 to 1100 MHz

TYPICAL PERFORMANCE DATA

Frequency (MHz)	Insertion Loss (dB)	Return Loss (dB)
600.00	0.70	11.42
700.00	0.50	13.14
800.00	0.35	16.75
825.00	0.45	18.23
850.00	0.44	19.80
875.00	0.34	22.25
900.00	0.37	25.70
1000.00	0.41	19.94
1100.00	0.71	12.88
1200.00	1.13	9.11





NOTES

A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.

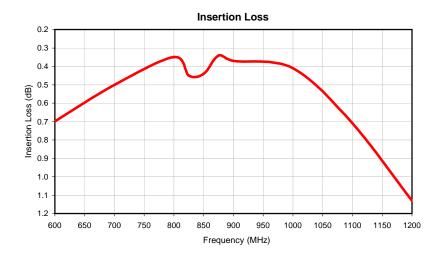
B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.

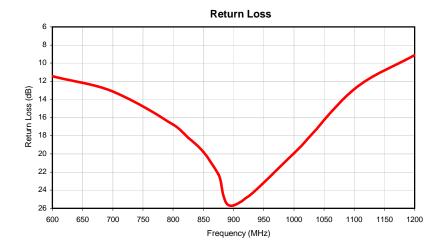
C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the standard. Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/terms/viewterm.html

Typical Performance Data

FREQUENCY (MHz)	INSERTION LOSS (dB)	RETURN LOSS (dB)
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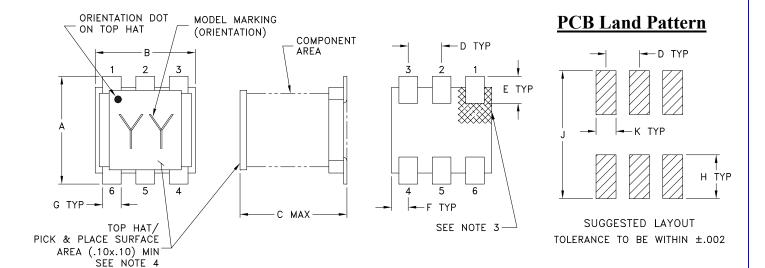


Case Style



DB1627

Outline Dimensions



CASE#	A	В	C	D	Е	F	G	Н	J	K	WT. GRAM
DB1627	.160	.150	.160	.050	.040	.025	.028	.065	.190	.030	15
DB1027	(4.06)	(3.81)	(4.06)	(1.27)	(1.02)	(0.64)	(0.71)	(1.65)	(4.83)	(0.76)	.13

Dimensions are in inches (mm). Tolerances: 2 Pl. \pm .01; 3Pl. \pm .005

Notes:

- 1. Case material: Plastic.
- 2. Termination finish:

For RoHS Case Styles: Tin plate over Nickel plate. All models, (+) suffix.

For RoHS-5 Case Styles: Tin-Lead plate. All models, no (+) suffix.

- 3 Orientation dot on top hat & orientation feature on substrate correspondence to pin #1.
- 4 Top-Hat total thickness: .013 inches MAX.





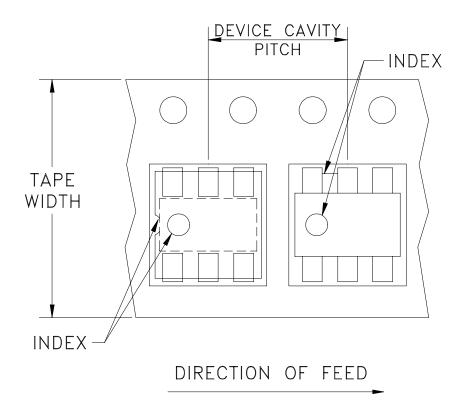
P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site

The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com

RF/IF MICROWAVE COMPONENTS

Tape & Reel Packaging TR-F47

DEVICE ORIENTATION IN T&R



Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel see note
12	8	13	1000, 2000
		7	20, 50, 100, 200, 500

Note: Please consult individual model data sheet to determine device per reel availability.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf



INTERNET http://www.minicircuits.com

P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661

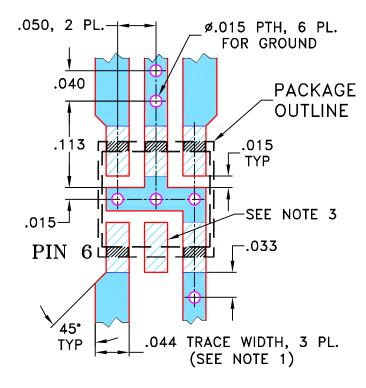
Distribution Centers NORTH AMERICA 800-654-7949 • 417-335-5935 • Fax 417-335-5945 • EUROPE 44-1252-832600 • Fax 44-1252-837010

Mini-Circuits ISO 9001 & ISO 14001 Certified

THIRD ANGLE PROJECTION	
Ψ	

		REVISIONS			
REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	M106563	NEW RELEASE	08/23/06	ΑV	IG

SUGGESTED MOUNTING CONFIGURATION FOR AT224/DB714 CASE STYLE, "gs/ha/hd" PIN CONNECTIONS (FOR SINGLE ENDED TO BALANCED APPLICATION)



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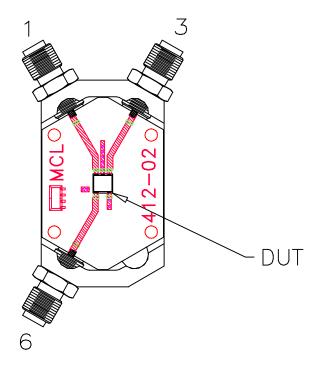
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DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

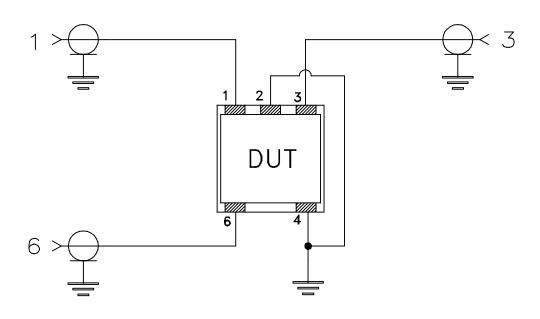
UNLESS OTHERWISE SPECIFIED)	INITIALS	DATE			. ~		• 4 ®		
DIMENSIONS ARE IN INCHES	DRAWN	AV	07/28/06		-1 Mini	ı — C	ircu	lts 13	Neptu	ne Avenue NY 11235
TOLERANCES ON:	CHECKED	IL	08/23/06					Dro	OKIJII	GCSII IN
3 PL DECIMALS ± .005	APPROVED	IG	08/23/06							
FRACTIONS ±				PL.	gs/ha/hd	. AT2	24/DB714	4. TC/T	CM.	TB-145
□ Mini	-Circuits ®],	6-77	,	-,	-,, -	,	
THIS DOCUMENT AND ITS CONTENTS EXCEPT FOR USE EXPRESSLY GRANTE				SIZE	CODE IDENT	DRAWING	NO.			REV:
AND THE UNITED STATES GOVERNMEN DESIGN, USE , MANUFACTURING AND THESE CONTENTS SHALL NOT BE USI	REPRODUCTION ID, DUPLICATED	RIGHTS THERETO. OR DISCLOSED TO	ANY OUTSIDE	A	15542	DRAWING	98-PL	-244		OR
PARTY, IN WHOLE OR IN PART, WITH				FILE:	98PL244	SCALE:	8:1	SHEET:	1	OF 1
	ASHEETA1.	WG REV:A	DATE:01/12/95		JUI DATT		0.1		1	V1 1

Evaluation Board and Circuit

For Pin Connections refer to Data Sheet of the DUT



TB-145



Schematic Diagram

Notes:

- 1. 50 Ohm SMA Female connectors.
- 2. PCB Material: Rogers RO4350B or its equivalent, III Mini-Circuits® Dielectric Constant=3.5, Thickness=.020"



Environmental Specifications

ENV02

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-20° to 85°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Thermal Shock	-55° to 100°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, except +100°C
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A
Marking Resistance to Solvents	Isopropyl alcohol + mineral spirits at 25°C; terpene defluxer at 25°C; distilled water + proylene glycol monomethyl ether + monoethanolamine at 63°C to 70°C	MIL-STD-202, Method 215

ENV02 Rev: A

02/25/11

M130240 File: ENV02.pdf